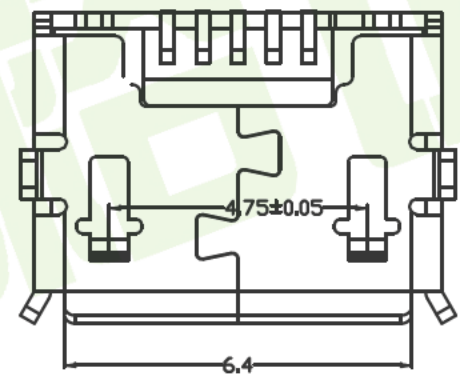
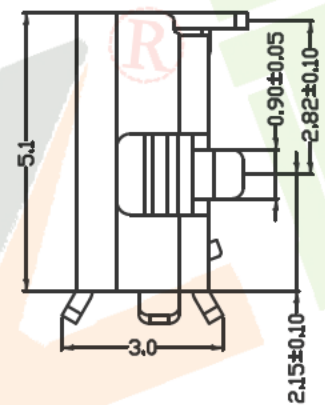
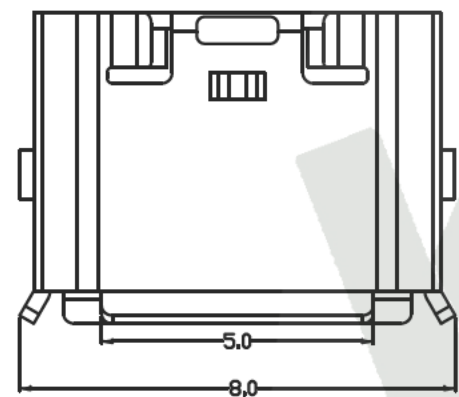
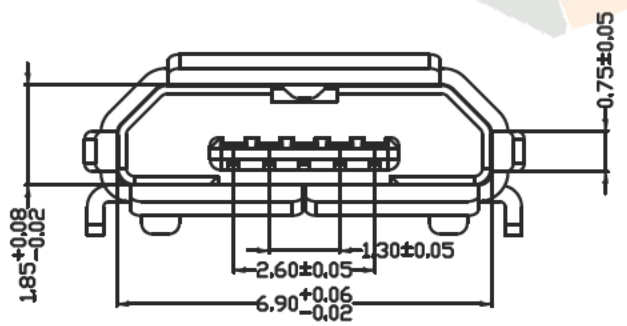


PCB LAYOUT



- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f,UL94v-0
 - Contact: copper alloy,t=0.15mm
 - Shell: copper alloySUS
 - Specification:
 - Current rating: 1 A Max.
 - Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - Contact resistance: 30 mW Max.
 - Insulation resistance: 100 MW Min.
 - Total mating force: 3.57 Kgf Max.
 - Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
 - Temperature range: -30°C~80°C



尺寸	允许公差
.x	±0.50
.x	±0.20
.xx	±0.10
.xxx	±0.03
角度	±1.00°

深圳市裕诚电子有限公司
SHENZHEN YUCHENG ELECTRONICS CO., LTD

图纸类型		图纸名称:	
产品工程图		MICRO 5P/F B 反向牛角内DIP 0.6(7.7*5.3)	
设计	陈雅 魏杰	产品料号	MICRO-NF51
审核	洪章波 2016.2.5	视图	版号: A/0